



DMWSH120H28SM4Q

1200V N-CHANNEL SILICON CARBIDE POWER MOSFET

Product Summary

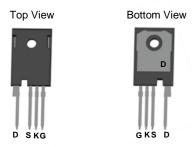
BV _{DSS}	R _{DS(ON)} Max	I _D T _C = +25°C		
1200V	28.5mΩ @V _{GS} = 15V	100A		

Description and Applications

This SiC MOSFET is designed to minimize the on-state resistance yet maintain superior switching performance, making it ideal for high-efficiency power-management applications.

- EV high-power DC-DC converters
- EV charging systems
- AC-DC traction inverters
- Automotive motor drivers

TO247-4 (Type WH)



Pin Configuration

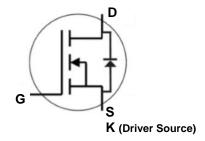
Features and Benefits

- Low On-Resistance
- High BV_{DSS} Rating for Power Application
- Low Input Capacitance
- Lead-Free Finish; RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- The DMWSH120H28SM4Q is suitable for automotive applications requiring specific change control; this part is AEC-Q101 qualified, PPAP capable, and manufactured in IATF 16949 certified facilities.

https://www.diodes.com/quality/product-definitions/

Mechanical Data

- Package: TO247-4
- Package Material: Molded Plastic, "Green" Molding Compound.
 UL Flammability Classification Rating 94V-0
- Terminal Connections: See Diagram
- Terminals: Finish Matte Tin Annealed over Copper Leadframe.
 Solderable per MIL-STD-202, Method 208 (2)
- Weight: 6.6 grams (Approximate)



Internal Schematic

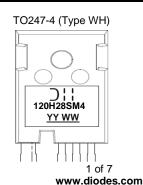
Ordering Information (Note 4)

Part Number	Backago	Packing		
Part Number	Package Qty.		Carrier	
DMWSH120H28SM4Q	TO247-4 (Type WH)	30 Pieces	Tube	

Notes:

- 1. EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant. All applicable RoHS exemptions applied.
- 2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.

Marking Information



D: I = Manufacturer's Marking
120H28SM4 = Product Type Marking Code
YYWW = Date Code Marking
YY = Last Two Digits of Year (ex: 23 = 2023)
WW = Week Code (01 to 53)



Maximum Ratings (@ $T_A = +25$ °C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit	
Drain-Source Voltage		V _{DSS}	1200	V
Gate-Source Voltage (Dynamic)		Vgss	+19/-8	V
Gate-Source Voltage (Static)		Vgss	+15/-4	V
Continuous Drain Current (Notes 5, 9)	$T_C = +25$ °C $T_C = +100$ °C	ID	100 70.8	А
Continuous Diode Forward Current (Note 5)	Is	87	A	
Pulsed Source Current (10µs Pulse, Duty Cycle = 1%) (Note 5)		Ism	430	А
Pulsed Drain Current (10µs Pulse, Duty Cycle = 1%) (Note 5)		I _{DM}	430	A

Thermal Characteristics (@TA = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit		
Total Power Dissipation (Note 5)	$T_C = +25^{\circ}C$	0	429	w	
Total Power Dissipation (Note 5)	T _C = +100°C	PD	214	l vv	
Thermal Resistance, Junction to Ambient (Note 6)	$R_{\theta JA}$	28.8	°C/W		
Thermal Resistance, Junction to Case (Note 5)	Rejc	0.35	C/VV		
Operating and Storage Temperature Range	TJ, TSTG	-55 to +175	°C		

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 8)							
Drain-Source Breakdown Voltage	BVDSS	1200	_	_	V	$V_{GS} = 0V, I_{D} = 100\mu A$	
Zero Gate Voltage Drain Current	IDSS	_	_	50	μA	$V_{DS} = 1200V, V_{GS} = 0V$	
Gate-Source Leakage	I _{GSS}	_	_	±250	nA	$V_{GS} = +15/-4V, V_{DS} = 0V$	
ON CHARACTERISTICS (Note 8)							
Gate Threshold Voltage	Vgs(th)	1.8	2.5	3.6	V	$V_{DS} = V_{GS}$, $I_D = 17.7 \text{mA}$	
Static Drain-Source On-Resistance	RDS(ON)	-	20	28.5	mΩ	$V_{GS} = 15V, I_{D} = 50A$	
Diode Forward Voltage	VsD	1	3.8	_	V	V _G S = -4V, I _S = 25A	
Transconductance	gfs	_	15	_	S	$V_{DS} = 20V, I_{D} = 50A$	
DYNAMIC CHARACTERISTICS (Note 7)							
Input Capacitance	C _{iss}	1	3944	_		V _{GS} = 0V, V _{DS} = 1000V,	
Output Capacitance	Coss	1	180	_	pF		
Reverse Transfer Capacitance	Crss	-	9.73	_		$V_{AC} = 25mV, f = 1MHz$	
Coss Stored Energy	E _{oss}		114.6	_	μJ		
Turn-On Switching Energy (Body Diode Forward)	Eon	_	744	_	μJ	$V_{GS} = -4V/+15V$, $V_{DS} = 800V$,	
Turn-Off Switching Energy (Body Diode Forward)	Eoff	_	1818	_		Rg = 5Ω , I _D = $50A$, L = 157μ H	
Gate Resistance	Rg	_	1.3	_	Ω	V _{AC} = 25mV, f = 1MHz	
Total Gate Charge	Qg	_	173.7	_		AVI. 45V. V. 600V.	
Gate-Source Charge	Qgs	_	51.9	_	nC	$V_{GS} = -4V/+15V$, $V_{DS} = 800V$, $I_{D} = 50A$	
Gate-Drain Charge	Q _{gd}	_	56.4	_		ID = JUA	
Turn-On Delay Time	td(on)	_	23.83	_			
Turn-On Rise Time	t _R	_	59.66	_	ns	$V_{GS} = -4V/+15V$, $V_{DD} = 800V$, $Rg = 5\Omega$, Inductive Load	
Turn-Off Delay Time	t _{D(OFF)}	_	48.00	_	115		
Turn-Off Fall Time	tF	_	12.52	_			
Body Diode Reverse-Recovery Time	t _{RR}	_	33.89	_	ns	V 4V/ V 000V/	
Body Diode Reverse-Recovery Charge	Qrr	_	317.93	_	nC	$V_{GS} = -4V$, $V_{DS} = 800V$, $I_{D} = 50A$, $di/dt = 2600A/\mu s$	
Body Diode Reverse-Recovery Current	I _{RRM}		18.76		Α	$-10 = 50A$, $al/al = 2600A/\mu s$	

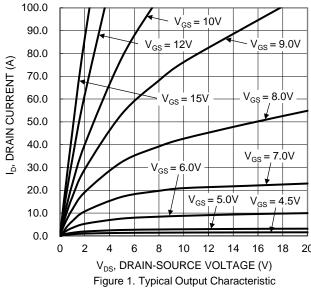
Notes:

- 5. Device mounted on an infinite heatsink.
- S. Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.
 Guaranteed by design. Not subject to production testing.
 Short duration pulse test used to minimize self-heating effect.

- Drain current limited by maximum junction temperature.







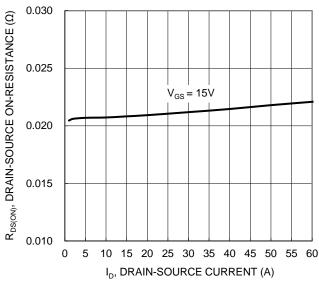


Figure 3. Typical On-Resistance vs. Drain Current and Gate Voltage

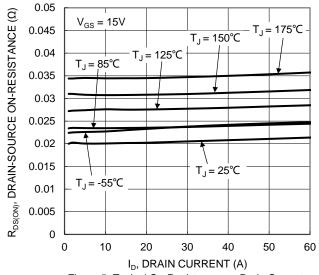
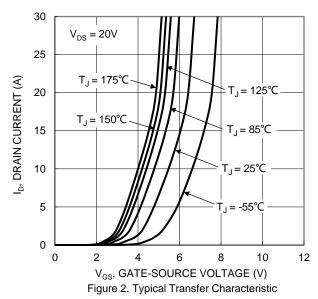
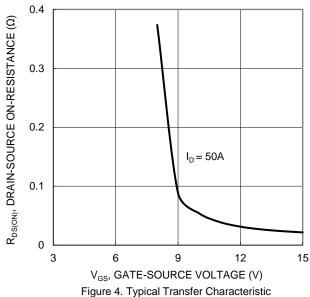


Figure 5. Typical On-Resistance vs. Drain Current and Temperature





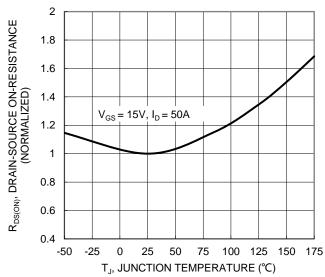


Figure 6. On-Resistance Variation with Temperature





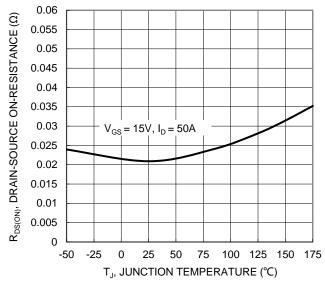


Figure 7. On-Resistance Variation with Temperature

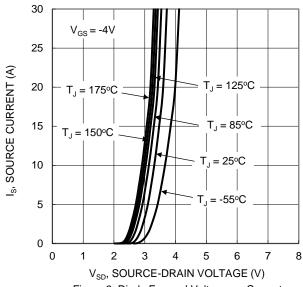


Figure 9. Diode Forward Voltage vs. Current

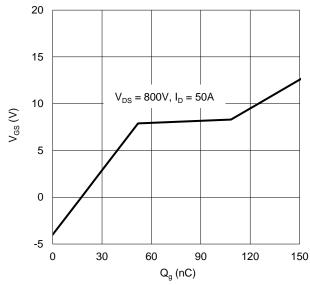


Figure 11. Gate Charge

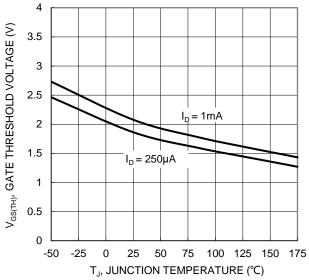


Figure 8. Gate Threshold Variation vs. Junction Temperature

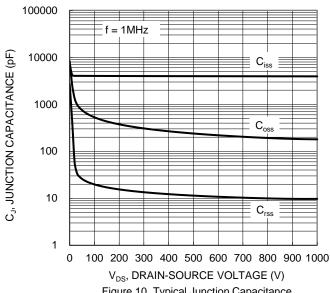
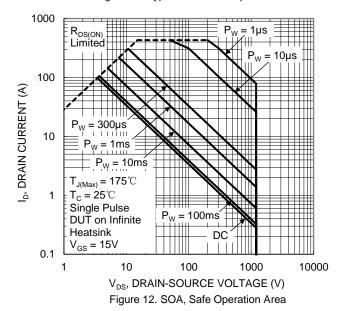


Figure 10. Typical Junction Capacitance





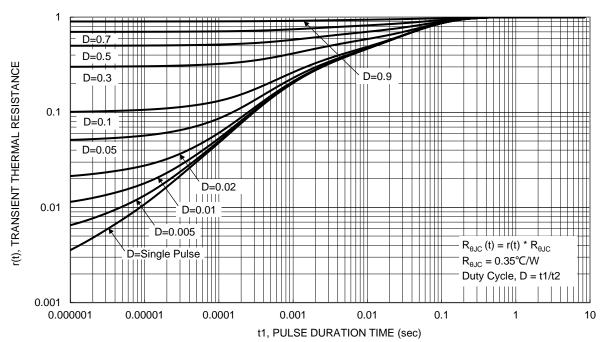


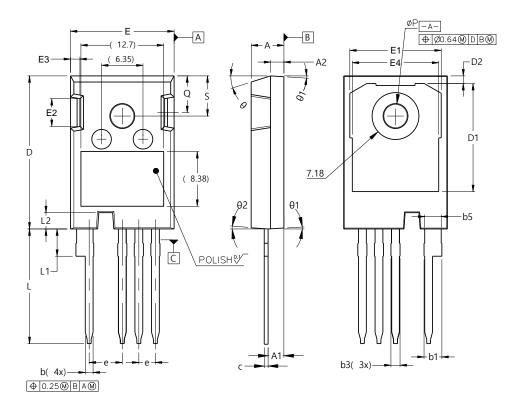
Figure 13. Transient Thermal Resistance



Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

TO247-4 (Type WH)



TO247-4 (Type WH)				
Dim	Min	Max		
Α	4.83	5.21		
A1	2.29	2.54		
A2	1.91	2.16		
b	1.07	1.33		
b1	2.39	2.94		
b3	1.07	1.60		
b5	2.39	2.69		
С	0.55	0.68		
D	23.30	23.60		
D1	16.25	17.65		
D2	0.95	1.25		
E	15.75	16.30		
E1	13.10	14.15		
E2	3.68	5.10		
E3	1.00	1.90		
E4	12.38	13.43		
е	2.54 BSC			
e1	5.08 BSC			
L L1	17.31	17.82		
L1	3.97	4.37		
L2	2.35	2.65		
ØP	3.51	3.65		
Q	5.49	6.00		
S	6.04	6.30		
θ	17.5° REF			
θ1	3.5° REF			
θ2	4° REF			
All Dimensions in mm				



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